| <del></del>   | Docket No.: 112895-006  |
|---|---|
| FORM PTO-1595 (Modified) (Rev. 03-01) OMB No. 0651-0027 (exp.5/31/2002) P08A/REV03  | U.S. DEPARTMENT OF COMMERCE   |
| Tab settings → → → ▼  | 6350 ▼ ▼ ▼  |
|   | Office: Please record the attached original documents or copy thereof.                                |
| 1. Name of conveying party(ies):  Keiji OGUMA  (A . L . L   | 2. Name and address of receiving party(ies):  Name: Eisai Co., Ltd.  Address: 6-10 Koishikawa 4-chome |
| Additional names(s) of conveying party(ies)   | Bunkyou-ku  |
| 3. Nature of conveyance:  |   |
|   |   |
| ☐ \$ecurity Agreement ☐ Change of Name  | City: <u>Tokyo 112-8088</u> State/Prov.:  |
| □ <b>O</b> ther   | Country: JAPAN ZIP:   |
| Execution Date: February 25, 2003   | Additional name(s) & address(es) ☐ Yes ☒ No   |
| If this document is being filed together with a new application,  Patent Application No. Filing date  | , the execution date of the application is:  B. Patent No.(s)   |
| 10/137,507 April 30, 2002  Additional numbers   | ☐ Yes ☒ No  |
| 5. Name and address of party to whom correspondence   | 6. Total number of applications and patents involved:   |
| concerning document should be mailed:   | o. Total name of applications and paragraph in the vote.  |
| Name: Robert M. Barrett   | 7. Total fee (37 CFR 3.41):\$ 40.00   |
| Registration No. 30,142   | ☑ Enclosed - Any excess or insufficiency should be  |
| Address: Bell, Boyd & Lloyd DLC   | credited or debited to deposit account  |
| P.O. Box 1135   | ☐ Authorized to be charged to deposit account   |
| 06/17/2003 ECDOPER 00000225 10137507  | 8. Deposit account number:  |
| FC:8021   | 02-1818   |
| Country: U.S.A. ZIP: 60690  | (Attach duplicate copy of this page if paying by deposit account)                                     |
|   | USE THIS SPACE  |
| 9. Statement and signature.  To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document. |   |
| Robert M. Barrett (Reg. No. 30,142)   | June 11, 2003   |
| Name of Person Signing  | Signature Date  |
| Total number of pages including or Mail documents to be recorded with   |   |

Mail documents to be recorded with required cover sheet information to:

Mail Stop Assignment Recordation Services
Director of the United States Patent and Trademark Office

REEL: 014173 FRAME: 0318

Docket Number: 112895-006

## ASSIGNMENT

WHEREAS, I, <u>Keiji Oguma</u>, as a named inventor (hereinafter referenced as ASSIGNOR), residing at the address stated next to my name, am the sole inventor of certain new and useful improvements in <u>"ISOLATION AND PURIFICATION OF CLOSTRIDIUM BOTULINUM TOXINS"</u> for which application for Letters Patent of the United States of America was executed by me on the date indicated next to my name and address below;

AND WHEREAS, Eisai Co., Ltd., a Japanese corporation with offices at 6-10 Koishikawa 4-chome, Bunkyou-ku, Tokyo 112-8088, (hereinafter referenced as ASSIGNEE) is desirous of acquiring fifty percent (50%) interest in, to and under said invention, said application disclosing the invention and in, to and under any Letters Patent or similar legal protection which may be granted therefor in the United States and in any and all foreign countries;

NOW THEREFORE, in consideration of the sum of One Dollar (\$1.00), and other good and valuable consideration, the receipt and sufficiency of which are hereby acknowledged, I, as the sole inventor as indicated below, by these presents do hereby assign, sell and transfer unto the said ASSIGNEE, its successors, assigns, and legal representatives, fifty percent (50%) of the right, title and interest in the said invention, said application, including any divisions and continuations thereof, and in and to any and all Letters Patent of the United States, and countries foreign thereto, which may be granted for said invention, and in and to any and all priority rights and/or convention rights under the International Convention for the Protection of Industrial Property, Inter-American Convention Relating to Patents, Designs and Industrial Models, and any other international agreements to which the United States of America adheres, and to any other benefits accruing or to accrue to me with respect to the filing of applications for patents or securing of patents in the United States and countries foreign thereto, and I hereby authorize and request the Commissioner of Patents to issue the said United States Letters Patent to said ASSIGNOR and ASSIGNEE, as joint owners of the whole right, title and interest thereto;

And I further agree to execute all necessary or desirable and lawful future documents, including assignments in favor of ASSIGNEE or its designee, as ASSIGNEE or its successors, assigns and legal representatives may from time-to-time present to me and without further remuneration, in order to perfect title in said invention, modifications, and improvements in said invention, applications and Letters Patent of the United States and countries foreign thereto;

And I further agree to properly execute and deliver and without further remuneration, such necessary or desirable and lawful papers for applications for foreign patents, for filing subdivisions of said application for patent, and or, for obtaining any reissue or reissues or any Letters Patent which may be granted for my aforesaid invention, as the ASSIGNEE thereof shall hereafter require and prepare at its own expense;

And I further agree that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said application, said invention and said Letters Patent and legal equivalents in foreign countries as may be known and accessible to me and will testify as to the same in any interference or litigation related thereto.

And I hereby covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment.

And I hereby authorize and request my attorney(s) of record in this application to insert the serial number and filing date of this application in the spaces as follows: Serial Number: <u>10/137,507</u>, Filing Date: <u>April 30, 2002</u>.

This assignment executed on the dates indicated below.

| KEIJI OGUMA                                      |                         |
|--|-------------------------|
| Name of first or sole inventor                   |                         |
| 82-45, Higashiune, Okayama, Okayama Pref., Japan |                         |
| Residence of first or sole inventor              |                         |
| Signature of first or sole inventor              | Date of this assignment |

Before me personally appeared the person whose name is subscribed to the foregoing instrument, and executed the foregoing instrument in my presence for the purpose contained therein, by signing his/her name hereto.

Date Signed

Tepi Oguma

Feb. 25, 2003

PATENT RECORDED: 06/16/2003 REEL: 014173 FRAME: 0319